

30V Half Bridge Dual N-Channel Enhancement Mode Power MOSFET



The NCEB301Q is designed to provide a high efficiency synchronous buck power stage with optimal layout and board space utilization. It includes two specialized MOSFETs in a dual Power DFN3X3 package. The Q1 "High Side" MOSFET is desgined to minimze switching losses. The Q2"Low Side" MOSFET uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge.

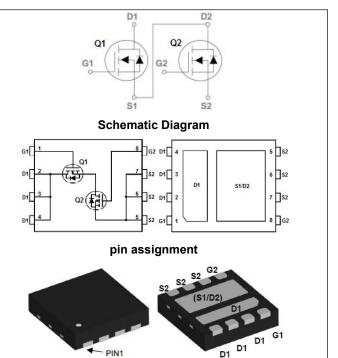
General Features

Q1 "High Side" MOSFET	Q2 "Low Side" MOSFET
• V _{DS} =30V,I _D =15A	V _{DS} =30V,I _D =20A
$R_{DS(ON)}$ <11.5m Ω @ V _{GS} =10V	$R_{DS(ON)}$ <8.2m Ω @ V _{GS} =10V
$R_{DS(ON)}$ <19m Ω @ V _{GS} =4.5V	$R_{DS(ON)}$ <13m Ω @ V _{GS} =4.5V
• Excellent gate charge x R _{DS(on)}	product(FOM)
• Very low on-resistance R _{DS(on)}	
 150 °C operating temperature 	
 Pb-free lead plating 	

• 100% UIS tested

Application

• Compact DC/DC converter applications



Top View 100% UIS TESTED!

100% ΔVds TESTED!

D1

Bottom View

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEB301Q	NCEB301Q	DFN3X3-8L	-	-	-

Absolute Maximum Ratings (T_c=25[°]Cunless otherwise noted)

Parame	Symbol	Q1	Q2	Unit	
Drain-Source Voltage		V _{DS}	30	30	V
Gate-Source Voltage		V _{GS}	±20	±20	V
Drain Current-Continuous (Note 2)	T _c =25°C		15	20	А
	T _c =100°C	ID	10.6	14.1	•
Drain Current -Pulsed (Note 1)		І _{дм}	60	80	A
Power Dissipation	T _c =25°C	PD	18	20	W
Operating Junction and Storage T	emperature Range	TJ,TSTG	-55 To 150	-55 To 150	°C

Thermal Characteristic

Parameter	Symbol	Тур	Max	Unit
Thermal Resistance, Junction-to-Case (Note 2) (Q1)	Rejc	6.5	7	°C/W
Thermal Resistance, Junction-to-Case (Note 2) (Q2)	R _{θJC}	6	6.3	°C/W



Q1 Electrical Characteristics (Tc=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	ı					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =250µA	1.0	1.5	2.2	V
Drain-Source On-State Resistance	P	V _{GS} =10V, I _D =10A	-	9.8	11.5	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =10A	-	15.3	19	mΩ
Gate resistance	Rg	V _{DS} =0V,V _{GS} =0V,F=1.0MHz	1.0	2.8	4.3	Ω
Forward Transconductance	g fs	V _{DS} =5V,I _D =10A	-	12	-	S
Dynamic Characteristics (Note4)		·				
Input Capacitance	Clss		-	690	-	pF
Output Capacitance	Coss	V _{DS} =15V,V _{GS} =0V, F=1.0MHz	-	105	-	pF
Reverse Transfer Capacitance	Crss		-	80	-	pF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	5	-	nS
Turn-on Rise Time	tr	V _{DD} =15V, R _L =0.75Ω	-	3.5	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =10V,R _G =3Ω	-	19	-	nS
Turn-Off Fall Time	t _f		-	3.5	-	nS
Total Gate Charge	Qg		-	15		nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =10A, V _{GS} =10V	-	2.5		nC
Gate-Drain Charge	Q _{gd}	V _{GS} -10V	-	3		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =10A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	15	А
Reverse Recovery Time	trr	TJ = 25°C, IF =10A	-	19	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	10	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, t ≤ 10 sec.

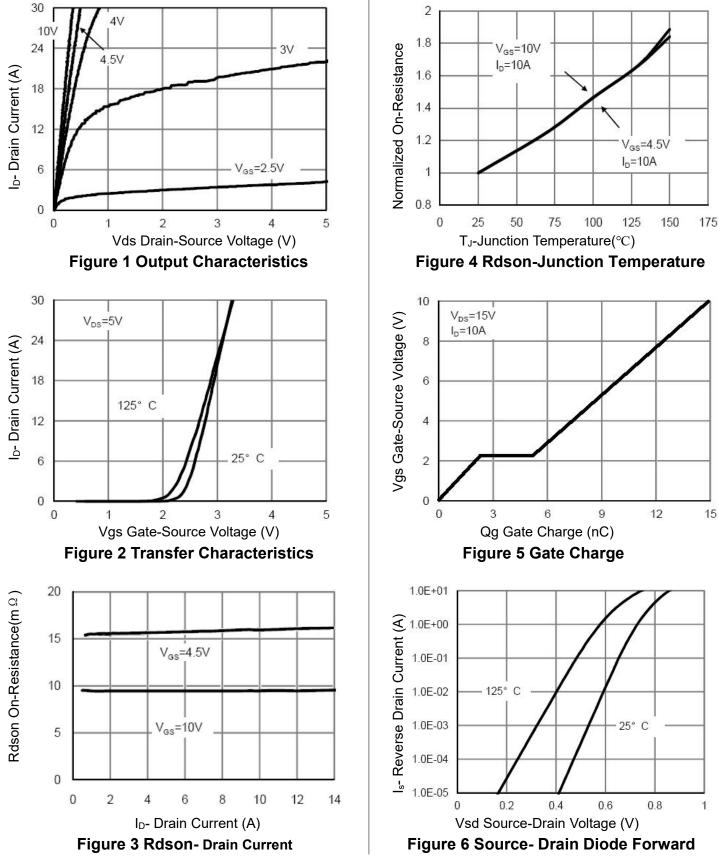
3. Pulse Test: Pulse Width ≤ 300 μ s, Duty Cycle ≤ 2%.

4. Guaranteed by design, not subject to production

5. EAS condition : Tj=25 $^\circ \!\! \mathbb{C}$,V_DD=15V,V_G=10V,L=0.5mH,Rg=25 Ω

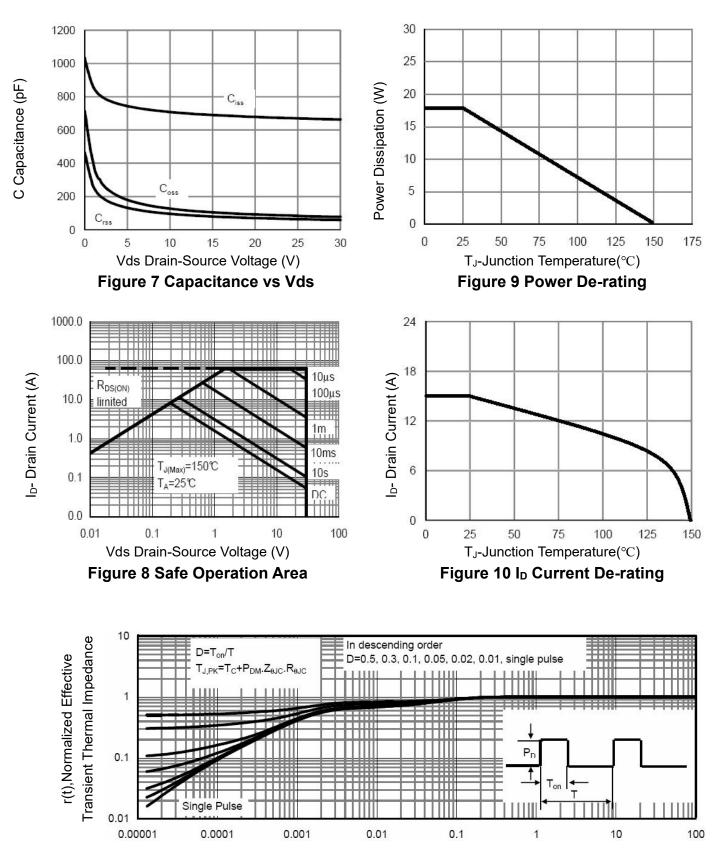


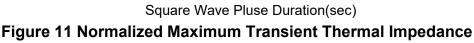
Q1Typical Electrical and Thermal Characteristics (Curves)





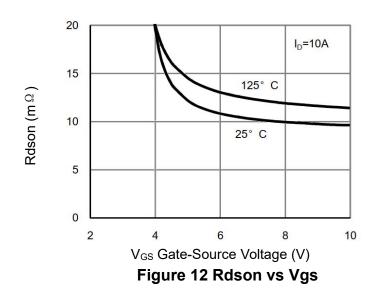
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Q2 Electrical Characteristics (TC=25 $^{\circ}$ Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Мах	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =250µA	1.0	1.5	2.2	V
Drain Courses On State Desistance	Б	V _{GS} =10V, I _D =10A	-	6.4	8.2	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =10A	-	10.0	13.0	mΩ
Gate resistance	Rg	V _{DS} =0V,V _{GS} =0V,F=1.0MHz	0.7	2.1	3.6	Ω
Forward Transconductance	g⊧s	V _{DS} =5V,I _D =10A	-	15	-	S
Dynamic Characteristics (Note4)		•	•			
Input Capacitance	Clss		-	960	-	pF
Output Capacitance	Coss	V _{DS} =15V,V _{GS} =0V,	-	157	-	pF
Reverse Transfer Capacitance	Crss	F=1.0MHz	-	140	-	pF
Switching Characteristics (Note 4)	·	·				
Turn-on Delay Time	t _{d(on)}		-	5	-	nS
Turn-on Rise Time	tr	V _{DD} =15V, R _L =0.75Ω	-	12	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =10V,R _G =3Ω	-	19	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Qg		-	24		nC
Gate-Source Charge	Q _{gs}	$V_{DS}=15V, I_{D}=10A,$	-	3		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	6		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =10A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	20	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =10A	-	19	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	10	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, $t \le 10$ sec.

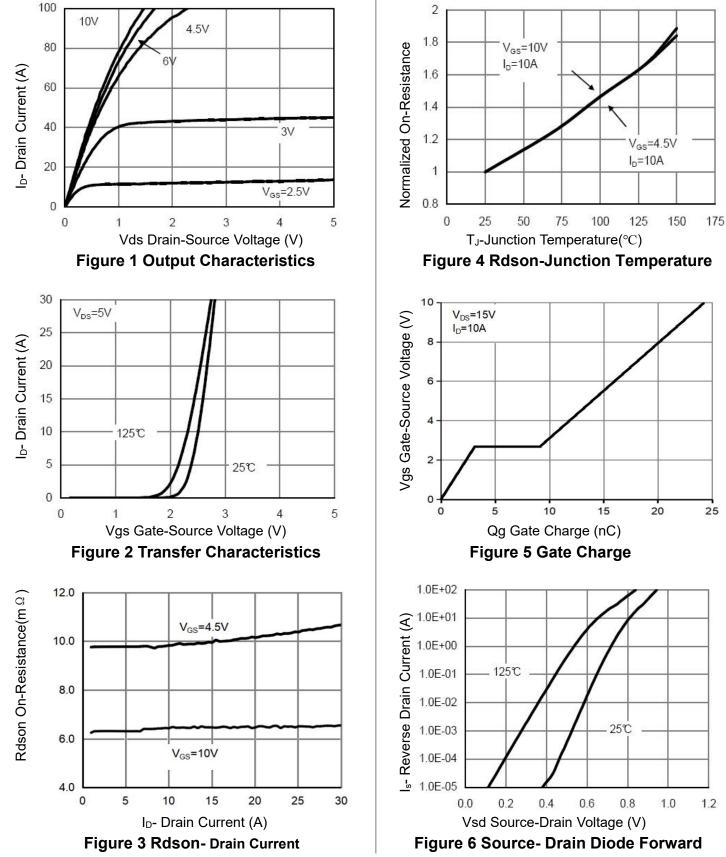
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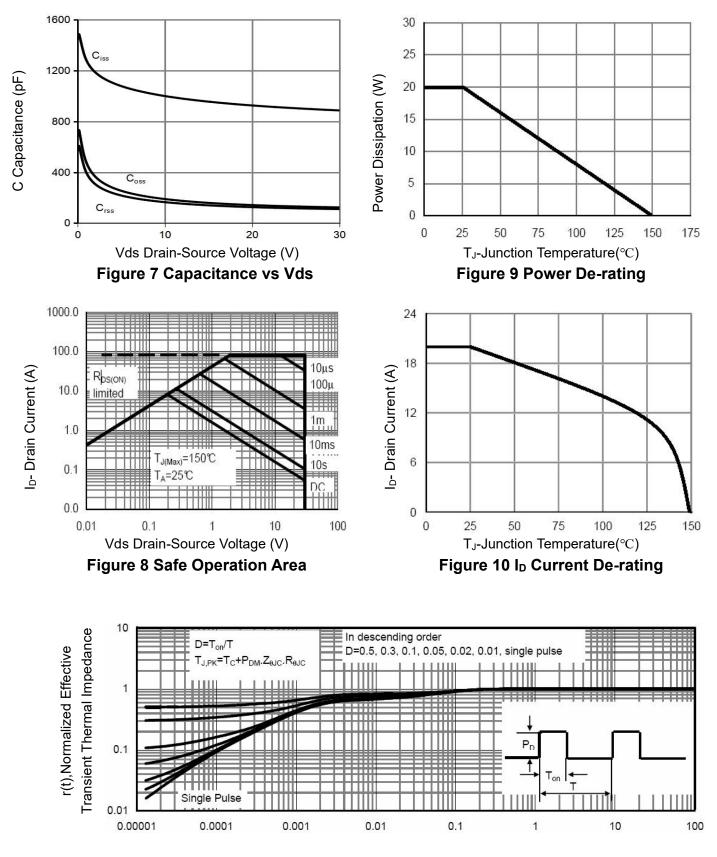






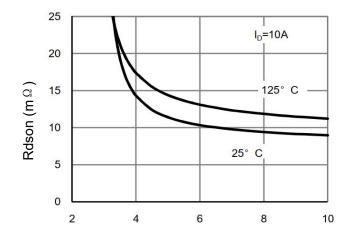


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Square Wave Pluse Duration(sec) Figure 11 Normalized Maximum Transient Thermal Impedance

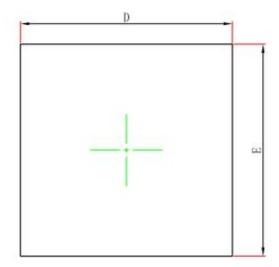


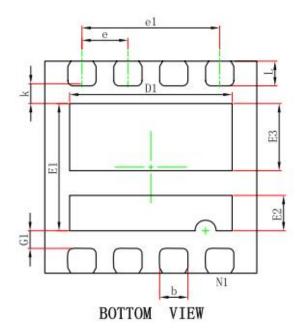


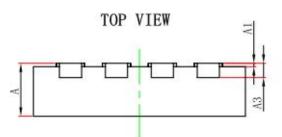
Vgs Gate-Source Voltage (V) Figure 12 Rdson vs Vgs



DFN3X3-8L Package Information







SIDE VIEW

Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	0.700	0.800	0.028	0.031	
A1	0.000	0.050	0.000	0.002	
A3	0.203	REF.	0.008	REF.	
D	2.950	3.050	0.116	0.120	
E	2.950	3.050	0.116	0.120	
D1	2.250	2.350	0.089	0.093	
E1	1.700	1.900	0.067	0.075	
E2	0.450	0.550	0.018	0.022	
E3	0.900	1.000	0.035	0.039	
k	0.200	0.300	0.008	0.012	
G1	0.200	0.300	0.008	0.012	
b	0.350	0.450	0.014	0.018	
е	0.650BSC		0.026BSC		
e1	1.95BSC		0.077	BSC	
L	0.300	0.400	0.012	0.016	



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